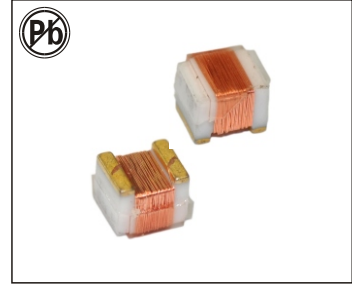


SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS AISC0805 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellent solderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

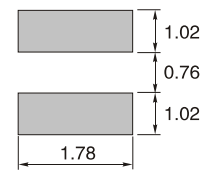
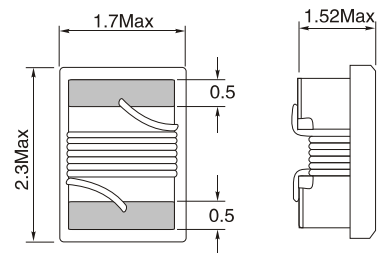
Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC0805-2N2□	2.2@250MHz	10	50@1500MHz	8.50	0.030	800
AISC0805-2N7□	2.7@250MHz	10,5	50@1500MHz	8.00	0.045	800
AISC0805-3N3□	3.3@250MHz	10	35@1500MHz	7.90	0.090	600
AISC0805-4N7□	4.7@250MHz	10	40@1000MHz	6.00	0.050	600
AISC0805-5N6□	5.6@250MHz	10,5	50@1000MHz	5.50	0.065	600
AISC0805-6N8□	6.8@250MHz	10,5	50@1000MHz	5.50	0.110	600
AISC0805-8N2□	8.2@250MHz	10,5	35@1000MHz	4.70	0.200	600
AISC0805-10N□	10@250MHz	10,5,2	50@500MHz	4.20	0.150	600
AISC0805-12N□	12@250MHz	10,5,2	50@500MHz	4.00	0.150	600
AISC0805-15N□	15@250MHz	10,5,2	45@500MHz	3.40	0.170	600
AISC0805-18N□	18@250MHz	10,5,2	55@500MHz	3.30	0.200	600
AISC0805-22N□	22@250MHz	10,5,2	55@500MHz	2.60	0.220	500
AISC0805-27N□	27@250MHz	10,5,2	55@500MHz	2.50	0.250	500
AISC0805-33N□	33@250MHz	10,5,2	55@500MHz	2.05	0.270	500
AISC0805-39N□	39@250MHz	10,5,2	55@500MHz	2.00	0.290	500
AISC0805-47N□	47@200MHz	10,5,2	55@500MHz	1.65	0.310	500
AISC0805-56N□	56@200MHz	10,5,2	55@500MHz	1.55	0.340	500
AISC0805-68N□	68@200MHz	10,5,2	55@500MHz	1.45	0.380	500
AISC0805-75N□	75@200MHz	10,5,2	55@500MHz	1.40	0.400	400
AISC0805-82N□	82@150MHz	10,5,2	55@500MHz	1.30	0.420	400
AISC0805-R10□	100@150MHz	10,5,2	50@500MHz	1.20	0.460	400
AISC0805-R12□	120@150MHz	10,5,2	45@250MHz	1.10	0.510	400
AISC0805-R15□	150@100MHz	10,5,2	45@250MHz	0.92	0.560	400
AISC0805-R18□	180@100MHz	10,5,2	45@250MHz	0.87	0.640	400
AISC0805-R22□	220@100MHz	10,5,2	40@250MHz	0.85	1.050	400
AISC0805-R27□	270@100MHz	10,5,2	40@250MHz	0.65	1.100	350
AISC0805-R33□	330@100MHz	10,5	40@250MHz	0.60	1.400	310
AISC0805-R39□	390@100MHz	10,5	40@250MHz	0.56	1.500	290
AISC0805-R47□	470@50MHz	10,5	33@100MHz	0.38	2.000	250
AISC0805-R56□	560@25MHz	10,5	23@50MHz	0.34	1.900	230
AISC0805-R68□	680@25MHz	10,5	23@50MHz	0.30	2.100	190
AISC0805-R75□	750@25MHz	10,5	23@50MHz	0.28	2.120	180
AISC0805-R82□	820@25MHz	10,5	23@50MHz	0.25	2.140	180
AISC0805-R91□	910@25MHz	10,5	20@50MHz	0.22	2.280	180
AISC0805-1R0□	1000@25MHz	10,5	20@50MHz	0.20	2.400	170
AISC0805-1R2□	1200@7.9MHz	10,5	18@50MHz	0.18	2.550	170
AISC0805-1R5□	1500@7.9MHz	10,5	18@50MHz	0.17	2.800	160
AISC0805-1R8□	1800@7.9MHz	10,5	18@50MHz	0.14	3.800	150
AISC0805-2R2□	2200@7.9MHz	10,5	16@7.9MHz	0.05	4.200	150

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
Inductance: HP4191A
Q:HP4291A
SRF:HP8753B
RDC:measured @ 25°C
- Operating Temperature:
Ceramic-55°C to +125°C
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260°C for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)



PCB LAYOUT

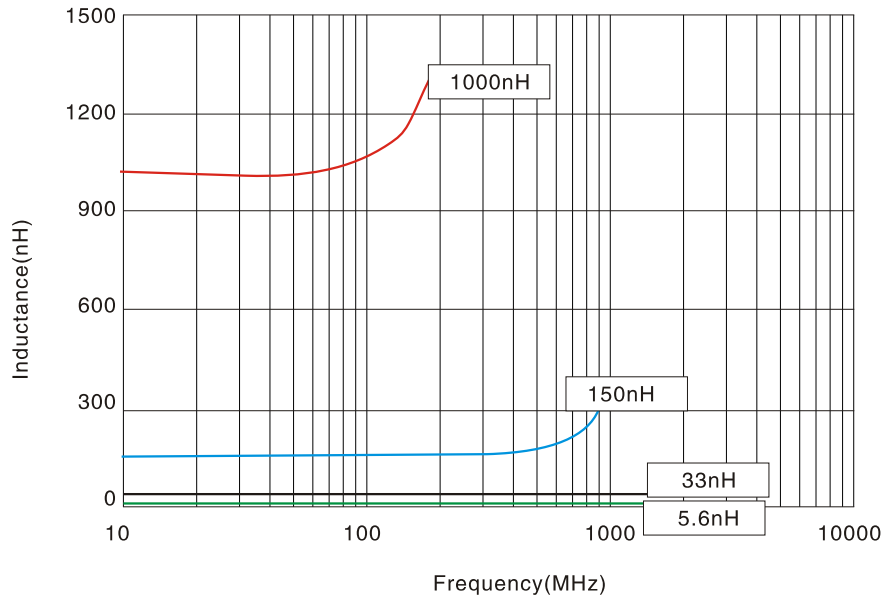
Winding



□ G= ± 2%, J= ± 5%, K= ± 10%,
M= ± 20%, N= ± 30%

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance vs Frequency



Q vs Frequency

